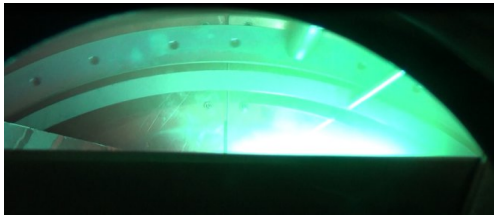


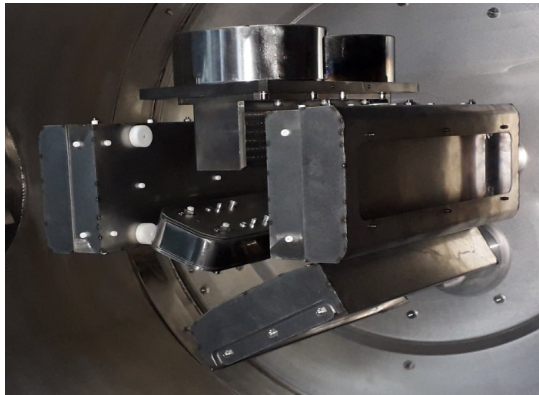
Magnetron M-310



Extended magnetron M-310 is designed for applying thin films of various materials on a substrate in a vacuum.

In the direct current mode, it is possible to deposit metals, alloys (including resistive ones) while maintaining the stoichiometric composition.

When using a pulsed medium-frequency power supply, it is possible to deposit semiconductors and dielectrics in a reactive mode from metal targets.



Parameter	Value
Maximum power	12 000 W
Maximum discharge current	15 A
Maximum supply voltage	800 V
Target size (length x width)	310 x 95
	<i>Height 6 mm (for magnetic, 10 for non-magnetic)</i>

Weight 8 kg (no more than)

Coolant consumption 2l/min при 3 kW,
4l/min - 7 КВт,
5l/min -12 КВт



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The design allows for various combinations of magnetron placement in the chamber.

